

COPIE JCL  
JAN 22 2002  
PATENT & TRADEMARK OFFICE

COPY OF PAPERS  
ORIGINALLY FILED

DOCKET NO. : MERCHANT 33-3-3

7823  
#20/Handt  
PATENT  
2/20/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Sailesh Merchant, *et al.*

Serial No.: 09/092,158

Filed: June 5, 1998

For: METHOD FOR THE FABRICATION OF CONTACTS IN AN INTEGRATED CIRCUIT DEVICE

Grp./A.U.: 2823

Examiner: Eaton, K.

Honorable Commissioner of Patents  
Washington, D.C. 20231

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231 on 12/4/01 (Date)  
(Printed or typed name of person signing the certificate)  
(Signature of the person signing the certificate)

Sir:

AMENDMENT UNDER 37 C.F.R. § 1.111

In response to the Examiner's Action mailed September 4, 2001, please amend the above-identified application as follows:

IN THE CLAIMS:

(1) Kindly amend Claim 1 as follows:

1. (Three Times Amended) A process for fabricating a contact in a semiconductor substrate having a contact opening formed therein, comprising:

C/